AMENDMENTS TO THE SPECIFICATION AND ABSTRACT:

Please replace the paragraph beginning at page 32, line 20, and ending at page 33, line 17 with the following rewritten paragraph:

Next, as shown in Fig. 5E, the IC chip 1 on which the bumps 3 have been formed through the aforementioned processes are aligned in position with the electrodes 5 that belong to the board 4 prepared through the aforementioned processes and correspond to the IC chip 1, and are pressed via the anisotropic conductive film sheet 10, by the heated bonding tool 8. Accordingly, commencement of application of heat to the circuit board 4 occurs substantially simultaneously with commencement of application of pressure to the circuit board. In this stage, the bump 3 is pressed against the electrode 5 of the board 4 with the head portion 3a of the bump 3 being deformed from the state of Fig. 3B to the state of Fig. 3C. In this stage, the load to be applied depends on the diameter of the bump 3, and the portion that belongs to the head portion 3a and is bent and folded is necessarily deformed as shown in Fig. 3C. In this case, when conductive particles 10a inside the anisotropic conductive film sheet 10 are obtained by plating resin balls with a metal as shown in Fig. 6, the conductive particles10a are required to be deformed. When the conductive particles 10a inside the anisotropic conductive film sheet 10 are metal particles of nickel or the like, it is required to apply a load such that the particles get into the bump 3 and the electrode 5 located on the board side. This load is required to be 20 (gf) at a minimum. The load may exceed 100 (gf) at a maximum.